

Abstract

The invention relates to the development and production of an equipment based on microelectronics components and semiconductor devices, and may be widely used in the production of multilayered connection plates as well as the connection structures for multichip modules. The multilayered connection plate comprises layers of a dielectric material having conductive paths on their surfaces, the layers being connection layers (1), (2), (3), and contact nodes (4), (5) in the form of metallized contacts mutually aligned and interconnected electrically and mechanically by a conductive binding material (11), (14), the contact nodes being made in the form of joints between the contacts. The second embodiment of the multilayered connection plate is characterized in that the conductive paths are placed on both sides of each connection layer (1), (2) and coupled with each other by metallized through holes (21), (19) within each layer.

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